

REMARKS

In the Advisory Action the Examiner referred to a telephonic interview on July 13, 2005 with applicant's representative, Thomas Krul. During that interview the applicant presented several arguments that distinguished the present invention over the cited art. Among those arguments was that the Goto and Yamazaki references do not disclose an anisotropic conductive adhesive agent for electrically connecting first and second terminals, the second terminal being thicker than the first, the first adhesive layer being applied to the first terminals, and second adhesive layer being applied to the second terminals, with the first adhesive layer specifically including a plurality of conductive particles. The Examiner did not seem to address these arguments in her Advisory Action. Instead, the Examiner suggested that applicant indicated that in the interview that amendments would be made to the claims to recite the boundary layer as shown in the preferred embodiments of Figures 8A and 8B. While applicant does not recollect making such statements, applicant has by way of this amendment included such limitations in the claims. For example, claim 1 now calls for "a boundary existing between the first adhesive layer and the second adhesive layer". The other independent claims, likewise, contain similar limitations.

The Examiner is also directed to other limitations in the claims which are believed to further define the relationship between the location of the conductive particles in the adhesive and the relative thicknesses of the two terminals. It is submitted that these

relationships are not disclosed or suggested by any of the references. For example claim 11 now recites that:

the first and second adhesive layers have outer surfaces; the outer surface of the first adhesive layer lying on a surface of the first substrate, and the outer surface of the second adhesive layer lying on an opposing surface of the second substrate; and

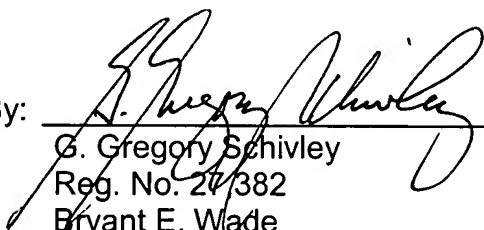
said conductive particles being arranged substantially in a plane spaced inboard from the outer surface of the first adhesive layer by a distance substantially the same as the thickness of the first terminal;

whereby the conductive particles remain substantially in place during assembly of the structure when the substrates are pressed together.

In view of the foregoing, favorable reconsideration of this application is respectfully requested. If the Examiner believes that personal contact would be advantageous to the disposition of this case, she is requested to call the undersigned at her earliest convenience.

Respectfully submitted,

Dated: Aug 19, 2005

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